

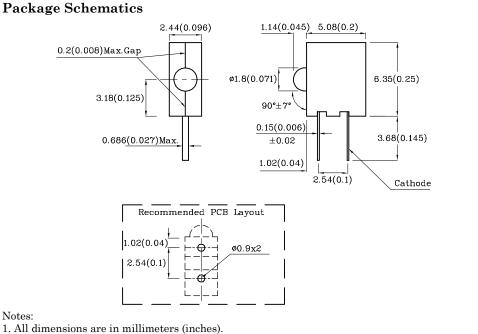
Part Number: XNH1ZUY46D

1.8mm One Position CBI Housing

Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- \bullet Reliable & robust
- RoHS Compliant





Notes:

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Yellow (GaAsP/GaP)	Unit		
Reverse Voltage	V_{R}	5	V		
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA		
Power Dissipation	\mathbf{P}_{D}	75	mW		
Operating Temperature	$T_{\rm A}$	T_A -40 ~ +85			
Storage Temperature	Tstg	$-40 \sim +85$	°C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

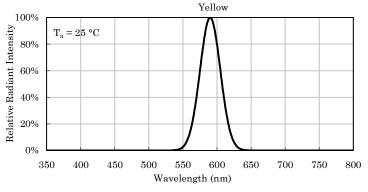
Operating Characteristics (T _A =25°C)		Yellow (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2.1	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	μΑ
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

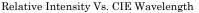
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XNH1ZUY46D	Yellow	GaAsP/GaP	Yellow Diffused	5*	9*	590*	40°

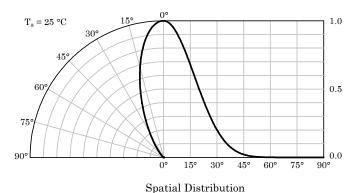
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



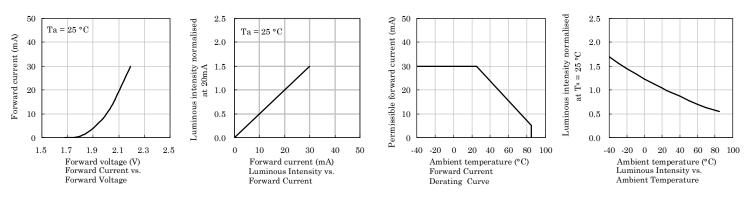
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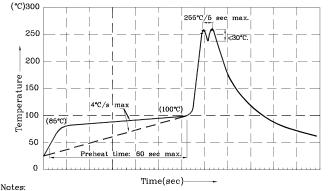








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

2. Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C. 4.Fixtures should not incur stress on the component when mounting and during soldering process.

during soldering process. 5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

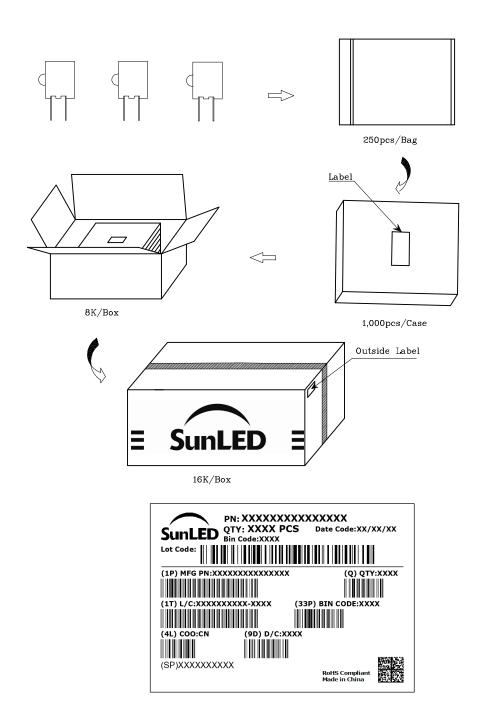
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



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- $6. \ Additional \ technical \ notes \ are \ available \ at \ \underline{https://www.SunLEDusa.com/TechnicalNotes.asp}$

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XDSA2715 V10-Z Layout: Maggie L.